

Electronic Acknowledgement Receipt

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Application Number:	10690782
Confirmation Number:	5611
Title of Invention:	Method for manufacturing a wafer level chip scale package
First Named Inventor:	Jin-Hyuk Lee
Customer Number:	20575
Filer:	Hosoon Lee/Stormi Davis
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		9903071c.pdf	964126	yes	13

	Multipart Description		
	Doc Desc	Start	End
	Miscellaneous Incoming Letter	1	1
	Amendment - After Non-Final Rejection	2	13
Warnings:			
Information:			
Total Files Size (in bytes):		964126	
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p><u>New Applications Under 35 U.S.C. 111</u> If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><u>National Stage of an International Application under 35 U.S.C. 371</u> If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p>			